

## Call for Papers

# *Special Section on Microwave and Millimeter-Wave Technologies*

The IEICE (Institute of Electronics, Information and Communication Engineers) Transactions on Electronics announces a forthcoming special section on "Microwave and Millimeter-Wave Technologies" to be published in **November 2027**.

Microwave and millimeter wave technologies support modern society in various fields. They have been used worldwide for information communication applications such as 5G and satellite communications, radar and positioning applications such as weather radar, medical monitoring, and GPS, and energy applications such as microwave ovens and plasma heating. In the future, they are expected to continue to create new applications including Beyond 5G/6G, IoT, intelligent mobility, health monitoring, wireless power transmission, and microwave chemical processes, and so on. Further research and development based on theory, design, simulation, measurement, system etc. is essential for microwave and millimeter-wave technologies to build a sustainable future society.

In such a background, this special section will present the latest high-quality research articles related to the area of microwave and millimeter-wave technologies. The section, therefore, solicits paper submission from all people engaged in the microwave and millimeter-wave technical fields.

### 1. Scope

Contributions are solicited in the following topics, but are not limited to:

- Active devices and circuits (low-noise devices and circuits, high-power devices and circuits, microwave tubes, amplifiers, mixers, oscillators, switches, MMICs, analog and mixed signal ICs, new energy IC, etc.)
- Passive components (waveguides and transmission lines, filters and resonators, directional couplers and hybrids, metamaterials, RF MEMS, LTCC devices, ferrite and acoustic wave components, packaging)
- Microwave/millimeter-wave/terahertz systems (5G/Beyond 5G/6G technologies, intelligent mobility technologies, sensing/imaging technologies, biological information sensing and monitoring, health care systems, RFID, etc.)
- Microwave/millimeter-wave/terahertz integrated antennas technologies
- Microwave/millimeter-wave/terahertz measurement technologies and packaging technologies
- Microwave photonics
- Wireless power transfer technologies
- Electronics simulation technologies
- Artificial intelligence (AI) and machine learning (ML) in microwave and EM design
- Microwave technologies for Quantum Computing

### 2. Submission Instructions

**The deadline for paper submission is November 16, 2026.** Acceptable manuscript type for the special section is either PAPER or BRIEF PAPER. Manuscripts should be prepared according to the style guidelines in the "Information for Authors" which is available at [https://www.ieice.org/eng/shiori/mokuji\\_es.html](https://www.ieice.org/eng/shiori/mokuji_es.html). The total length of the manuscript for PAPER should not exceed 8 printed pages, and that for BRIEF PAPER should not exceed 4 printed pages. It is noted that the Special Section will accept only via electronic submission. Prospective authors are requested to carefully follow the submission process described below. Please submit a paper via the IEICE website [https://review.ieice.org/regist/regist\\_baseinfo\\_e.aspx](https://review.ieice.org/regist/regist_baseinfo_e.aspx). Please choose the [Special-MM] Microwave and Millimeter-Wave Technologies as a "Journal/ Section" on the online screen. DO NOT CHOOSE [Regular-EC].

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